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| Chip Scale Review **2015 Editorial Calendar** | |
| **January  February** | |
| Semiconductor industry market update | * **SEMI European 3D TSV Summit**   Grenoble, France (Jan 19-21)   * **APEX Expo**   San Diego, CA (February 24-26)   * **BiTS Workshop**   Mesa, AZ (March 15-18)   * **IMAPS Device Packaging (DPC)**   Fountain Hills, AZ (March 16-19)   * **SEMICON China**   Shanghai China (March 17-19)   * **Productronica China**   Shanghai China (March 17-19) |
| Next generation device packaging |
| 3D TSVs |
| Bonding challenges for 3D ICs |
| 3D topography inspection for HVM |
| MEMS packaging technologies |
| Wafer probing |
| Advances in test and burn-in sockets |

**International Directory of Test and Burn-in Socket Suppliers *Ad Space Close Jan 6 - Ad Materials Deadline Jan 9***

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| **March  April** | |
| Future of mobile packaging & integration challenges | * **SEMICON South East Asia**   Penang, Malaysia (Apr 22-24) |
| RF probe technologies |
| Electronic packaging materials |
| FOWLP technology |
| Flip-chip packaging |
| 3D stacked ICs |
| Cu pillar technology |
| OSATS update |

**International Directory of IC Packaging Foundries  *Ad Space Close Feb 13*** *-* ***Materials Close Feb 19***

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| **May  June** | |
| Interconnect technology | * **MEPTEC**   **MEMS Technology**  San Jose, CA (May 20)  **IoT Symposium**  San Jose, CA (May 21)   * **ECTC**   San Diego, CA (May 26-29)   * **IMAPS Advanced Technology Workshop**   Dearborn, MI (June 3-4)   * **IEEE/SW Test Workshop (SWTW)**   San Diego, CA (June 7-10)   * **SEMI – Packaging Technical Seminar**   Porto, Portugal (June 18)   * **SEMICON West**   San Francisco, CA (July 14-16) |
| Thermal management of ICs |
| Interposer reliability |
| Wafer-level CSPs |
| Thin wafer-handling |
| MEMS Report Card |
| Dispensing technologies |
| Reducing the cost-of-test |
| Burn-in & test of packaged ICs\* |
| Inline monitoring of advanced packaging processes |  |

\*Awarded to best paper from BiTS Workshop 2015  ***Ad Space Close April 4 - Ad Materials Close April 10***

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| **Chip Scale Review**  **2015 Editorial Calendar** | |
| **July  August** | |
| Plasma cleaning technologies | * **SEMICON Taiwan**   Taipei, Taiwan (Sept 2-4)   * **MEPTEC**   **Medical Microelectronics Conference**  Portland, OR (Sept 16-17)   * **SEMI European MEMS Summit**   Milan, Italy (Sept 17-18) |
| Failure analysis |
| Collaboration in materials and processing technology |
| Metrology & defect inspection |
| Discrete power devices |
| Cu pillar bumping |
| MEMS IoT |
| Solder reliability |  |

***Ad Space Close Jun 6 - Ad Materials Close Jun 12***

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| **September  October** | |
| System scaling for smart mobile systems | * **SEMICON Europa** * Dresden, Germany (Oct 6-8) * **International Test Conference (ITC)**   Anaheim, CA (Oct 6 - 8)   * **IWLPC-International Wafer-Level**   **Packaging Conference & Exhibition**  San Jose, CA (Oct 13 -15)   * **IMAPS 2015**   Orlando, FL (Oct 26-29 )   * **Productronica**   Munich, Germany (Nov 10-13)   * **MEMS Executive Congress**   Napa, CA (TBD) |
| Interposers |
| Next generation SiP |
| Wafer-level packaging processes and performance |
| Test trends |
| Fan out wafer level packaging |
| Wirebonding |
| Design-for-test for stacked ICs |  |
| Packaging, assembly and test in Europe |  |

***Ad Space Close Aug 15 - Ad Materials Close Aug 21***

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| **November  December** | |
| Recent advances in 3D package reliability | * **RTI 3D ASIP Conference**   Burlingame, CA (Dec 9-11)   * **SEMICON Japan**   Tokyo, Japan (Dec 16-18)   * **SEMI European 3D TSV Summit 2016**   Grenoble, France (TBD) |
| Die stacking |
| Heterogeneous integration |
| Future of packaging |
| 3D IC standards update |
| Underfill, encapsulants, and adhesives |
| PoP |
| MEMS automotive applications |  |

***Ad Space Close Oct 10 - Materials Close Oct 16***

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